# **High Voltage Transistors**

## **NPN Silicon**

#### **Features**

• These are Pb-Free Devices\*



Rating	Symbol	Value	Unit
Collector - Emitter Voltage MPSA43 MPSA42	V <sub>CEO</sub>	200 300	Vdc
Collector - Base Voltage MPSA43 MPSA42	V <sub>CBO</sub>	200 300	Vdc
Emitter - Base Voltage	V <sub>EBO</sub>	6.0	Vdc
Collector Current - Continuous	I <sub>C</sub>	500	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	625 5.0	mW mW/°C
Total Device Dissipation @ T <sub>C</sub> = 25°C Derate above 25°C	P <sub>D</sub>	1.5 12	W mW/°C
Operating and Storage Junction Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C

#### THERMAL CHARACTERISTICS

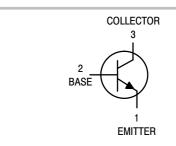
Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction-to-Ambient	$R_{\theta JA}$	200	°C/W
Thermal Resistance, Junction-to-Case	$R_{ heta JC}$	83.3	°C/W

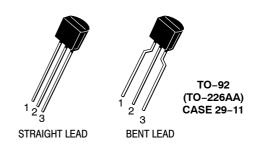
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



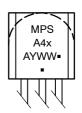
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#### MARKING DIAGRAM



x = 2 or 3
 A = Assembly Location
 Y = Year
 WW = Work Week
 = Pb-Free Package

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 3 of this data sheet.

<sup>\*</sup>For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

## **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Max	Unit
OFF CHARACTERISTICS		•		•	•
Collector – Emitter Breakdown Voltage (Note 1) $(I_C = 1.0 \text{ mAdc}, I_B = 0)$	MPSA42 MPSA43	V <sub>(BR)</sub> CEO	300 200	- -	Vdc
Collector – Base Breakdown Voltage ( $I_C = 100 \mu Adc, I_E = 0$ )	MPSA42 MPSA43	V <sub>(BR)CBO</sub>	300 200	- -	Vdc
Emitter – Base Breakdown Voltage ( $I_E = 100 \mu Adc$ , $I_C = 0$ )		V <sub>(BR)EBO</sub>	6.0	-	Vdc
Collector Cutoff Current $(V_{CB} = 200 \text{ Vdc}, I_E = 0)$ $(V_{CB} = 160 \text{ Vdc}, I_E = 0)$	MPSA42 MPSA43	I <sub>CBO</sub>	_ _	0.1 0.1	μAdc
Emitter Cutoff Current $(V_{EB} = 6.0 \text{ Vdc}, I_C = 0)$ $(V_{EB} = 4.0 \text{ Vdc}, I_C = 0)$	MPSA42 MPSA43	I <sub>EBO</sub>	_ _	0.1 0.1	μAdc
ON CHARACTERISTICS (Note 1)					
DC Current Gain $ \begin{aligned} &(I_C=1.0 \text{ mAdc, V}_{CE}=10 \text{ Vdc})\\ &(I_C=10 \text{ mAdc, V}_{CE}=10 \text{ Vdc})\\ &(I_C=30 \text{ mAdc, V}_{CE}=10 \text{ Vdc}) \end{aligned} $		h <sub>FE</sub>	25 40 40	- - -	_
Collector – Emitter Saturation Voltage (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 2.0 mAdc)	MPSA42 MPSA43	V <sub>CE(sat)</sub>		0.5 0.4	Vdc
Base–Emitter Saturation Voltage (I <sub>C</sub> = 20 mAdc, I <sub>B</sub> = 2.0 mAdc)		V <sub>BE(sat)</sub>	-	0.9	Vdc
SMALL-SIGNAL CHARACTERISTICS					
Current – Gain – Bandwidth Product (I <sub>C</sub> = 10 mAdc, V <sub>CE</sub> = 20 Vdc, f = 100 MHz)		f <sub>T</sub>	50	-	MHz
Collector-Base Capacitance (V <sub>CB</sub> = 20 Vdc, I <sub>E</sub> = 0, f = 1.0 MHz)	MPSA42 MPSA43	C <sub>cb</sub>	_ _	3.0 4.0	pF

<sup>1.</sup> Pulse Test: Pulse Width  $\leq$  300  $\mu$ s, Duty Cycle  $\leq$  2%.

#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MPSA42G	TO-92 (Pb-Free)	5000 Units / Box
MPSA42RL1G	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA42RLRAG	TO-92 (Pb-Free)	2000 / Tape & Reel
MPSA42RLRMG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA42RLRPG	TO-92 (Pb-Free)	2000 / Ammo Pack
MPSA42ZL1G	TO-92 (Pb-Free)	2000 / Ammo Pack

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

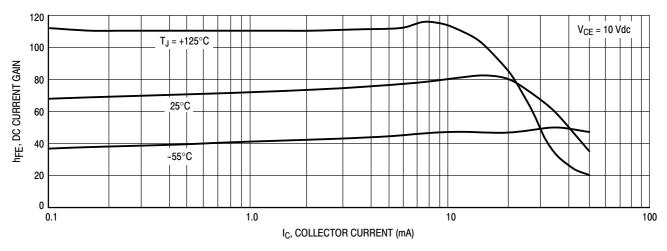


Figure 1. DC Current Gain

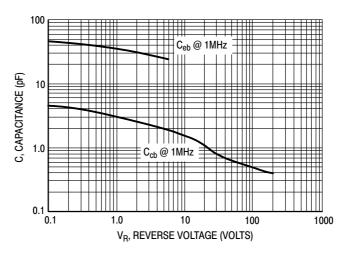


Figure 2. Capacitance

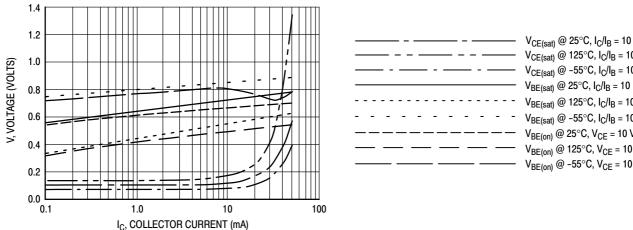


Figure 3. "ON" Voltages

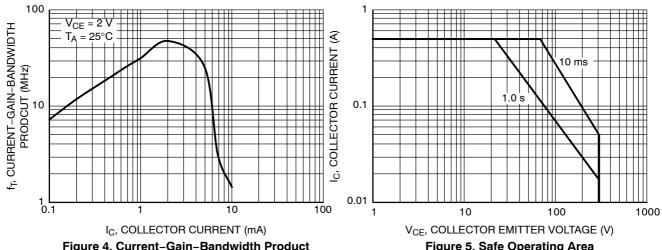
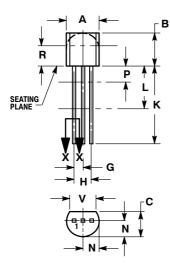


Figure 4. Current-Gain-Bandwidth Product

Figure 5. Safe Operating Area

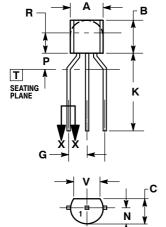
#### PACKAGE DIMENSIONS

TO-92 (TO-226) CASE 29-11 **ISSUE AN** 

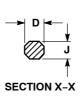


STRAIGHT LEAD





**BENTIFAD** 



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: INCH.
  CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
  LEAD DIMENSION IS UNCONTROLLED IN P AND
- BEYOND DIMENSION K MINIMUM

	INCHES		MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
P		0.100		2.54
R	0.115		2.93	
٧	0.135		3.43	

STYLE 1:

PIN 1. EMITTER 2. BASE

3. COLLECTOR

- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
  CONTROLLING DIMENSION: MILLIMETERS.
- CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED
- LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	MILLIMETERS		
DIM	MIN	MAX	
Α	4.45	5.20	
В	4.32	5.33	
С	3.18	4.19	
D	0.40	0.54	
G	2.40	2.80	
J	0.39	0.50	
K	12.70		
N	2.04	2.66	
P	1.50	4.00	
R	2.93		
V	3.43		

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